ES_LPC112x

Errata sheet LPC112x

Rev. 1 — 11 February 2015 **Errata sheet**

Document information

Info	Content
Keywords	LPC1125JBD48/303 and LPC1124JBD48/303 errata.
Abstract	This errata sheet describes both the known functional problems and any deviations from the electrical specifications known at the release date of this document. Each deviation is assigned a number and its history is tracked in a table at the end of the document.

Revision history

Rev	Date	Description
1	20150211	• Initial version

Contact information

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1. Product identification

The LPC1125 devices typically have the following top-side marking:

LPC1125x

/xxx

xxxxxxx

xxYYWWxR[x]

The last letter in the last line (field 'R') will identify the device revision. This Errata Sheet covers the following revisions of the LPC1125:

Table 1. Device revision table

Revision identifier (R)	Revision description
'A'	Initial device revision

Field 'YY' states the year the device was manufactured. Field 'WW' states the week the device was manufactured during that year.

2. Errata overview

Table 2. Functional problems table

Functional problems	Short description	Revision identifier	Detailed description
ADC.1	External sync inputs not operational	'A'	Section 3.1
ADC.2	A/D Global Data register should not be used with burst mode or hardware triggering.	'A'	Section 3.2
I2C.1	In the slave-transmitter mode, the device set in the monitor mode must write a dummy value of 0xFF into the DAT register.	'A'	Section 3.3
DPD.1	Deep power-down mode is not functional outside certain voltage and temperature ranges.	'A'	Section 3.4

Table 3. AC/DC deviations table

AC/DC deviations	Short description	Revision identifier	Detailed description
n/a	n/a	n/a	n/a

Table 4. Errata notes

Note	Short description	Revision identifier	Detailed description
n/a	n/a	n/a	n/a

3. Functional problems detail

3.1 ADC.1: External sync inputs not operational

Introduction:

In software-controlled mode (BURST bit is 0), the 10-bit ADC can start conversion by using the following options in the A/D Control Register:

26:24	START		When the BURST bit is 0, these bits control whether and when an A/D conversion is started:	0
		0x0	No start (this value should be used when clearing PDN to 0).	
		0x1	Start conversion now.	
		0x2	Start conversion when the edge selected by bit 27 occurs on PIO0_2/SSEL/CT16B0_CAP0.	
		0x3	Start conversion when the edge selected by bit 27 occurs on PIO1_5/DIR/CT32B0_CAP0.	
		0x4	Start conversion when the edge selected by bit 27 occurs on CT32B0_MAT0.	
		0x5	Start conversion when the edge selected by bit 27 occurs on CT32B0_MAT1.	
		0x6	Start conversion when the edge selected by bit 27 occurs on CT16B0_MAT0.	
		0x7	Start conversion when the edge selected by bit 27 occurs on CT16B0_MAT1.	

Problem:

The external start conversion feature, AD0CR:START = 0x2 or 0x3, may not work reliably and ADC external trigger edges on PIO0_2 or PIO1_5 may be missed. The occurrence of this problem is peripheral clock (pclk) dependent. The probability of error (missing a ADC trigger from GPIO) is estimated as follows:

- For PCLK_ADC = 50 MHz, probability error = 6 %
- For PCLK_ADC = 12 MHz, probability error = 1.5 %

The probability of error is not affected by the frequency of ADC start conversion edges.

Work-around:

In software-controlled mode (BURST bit is 0), the START conversion options (bits 26:24 set to 0x1 or 0x4 or 0x5 or 0x6 or 0x7) can be used. The user can also start a conversion by connecting an external trigger signal to a capture input pin (CAPx) from a Timer peripheral to generate an interrupt. The timer interrupt routine can then start the ADC conversion by setting the START bits (26:24) to 0x1. The trigger can also be generated from a timer match register.

3.2 ADC.2: A/D Global Data register should not be used with burst mode or hardware triggering

Introduction:

On the LPC1125, the START field and the BURST bit in the A/D control register specify whether A/D conversions are initiated via software command, in response to some hardware trigger, or continuously in burst ("hardware-scan") mode. Results of the ADC conversions can be read in one of two ways. One is to use the A/D Global Data Register to read all data from the ADC. Another is to use the individual A/D Channel Data Registers.

Problem:

If the burst mode is enabled (BURST bit set to ‘1’) or if hardware triggering is specified, the A/D conversion results read from the A/D Global Data register could be incorrect. If conversions are only launched directly by software command (BURST bit = '0' and START = ‘001’), the results read from the A/D Global Data register will be correct provided the previous result is read prior to launching a new conversion.

Work-around:

When using either burst mode or hardware triggering, the individual A/D Channel Data registers should be used instead of the A/D Global Data register to read the A/D conversion results.

3.3 I2C.1: In the slave-transmitter mode, the device set in the monitor mode must write a dummy value of 0xFF into the DAT register

Introduction:

The I2C monitor allows the device to monitor the I2C traffic on the I2C bus in a non-intrusive way.

Problem:

In the slave-transmitter mode, the device set in the monitor mode must write a dummy value of 0xFF into the DAT register. If this is not done, the received data from the slave device will be corrupted. To allow the monitor mode to have sufficient time to process the data on the I2C bus, the device may need to have the ability to stretch the I2C clock. Under this condition, the I2C monitor mode is not 100% non-intrusive.

Work-around:

When setting the device in monitor mode, enable the ENA_SCL bit in the MMCTRL register to allow clock stretching.

Software code example to enable the ENA_SCL bit:

```
LPC_I2C_MMCTRL |= (1<<1); //Enable ENA_SCL bit
```

In the I2C ISR routine, for the status code related to the slave-transmitter mode, write the value of 0xFF into the DAT register to prevent data corruption. In order to avoid stretching the SCL clock, the data byte can be saved in a buffer and processed in the Main loop. This ensures the SI flag is cleared as fast as possible.

Software code example for the slave-transmitter mode:

```
case 0xA8:     // Own SLA + R has been received, ACK returned
case 0xB0:
case 0xB8:     // data byte in DAT transmitted, ACK received
case 0xC0:     // (last) data byte transmitted, NACK received
case 0xC8:     // last data byte in DAT transmitted, ACK received
    DataByte = LPC_I2C->DATA_BUFFER;//Save data. Data can be process in Main loop
    LPC_I2C->DAT = 0xFF;            // Pretend to shift out 0xFF
    LPC_I2C->CONCLR = 0x08;         // clear flag SI
break;
```

3.4 DPD.1

Introduction:

The LPC112x has a supply voltage (V_{DD}) from 1.8 V to 3.6 V and can operate from -40 °C to 105 °C. The LPC112x supports three reduced power modes (Sleep, Deep-sleep, Power-down and Deep power-down mode). Deep power-down mode allows for maximal power savings where the entire system is shut down except for the general purpose registers in the PMU. Only the general purpose registers in the PMU maintain their internal states in Deep power-down mode.

Problem:

At temperatures <= 25 °C, the deep power-down mode is not functional if the V_{DD} supply voltage is greater than 3.55 V. At temperatures > 25 °C, the Deep power-down mode is not functional if the V_{DD} supply voltage is greater than 3.5 V.

Work-around:

For temperatures 25 °C and below, ensure that the supply voltage is not above 3.55 V (V_{DD} = 1.8 V to 3.55 V) when using Deep power-down mode. For temperatures higher than 25 °C, ensure that the supply voltage is not above 3.5 V (V_{DD} = 1.8 V to 3.5 V) when using Deep power-down mode.

4. AC/DC deviations detail

No known errata.

5. Errata notes

5.1 Note.1

The General Purpose I/O (GPIO) pins have configurable pull-up/pull-down resistors where the pins are pulled up to the V_{DD} level by default. During power-up, an unexpected glitch (low pulse) could occur on the port pins as the V_{DD} supply ramps up.

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